



PART NO. : TD04-2006QRL

16PIN DIP ISOLATION MODULE
MEET REQUIREMENTS OF 10BASE-T
FILTERLESS SOLUTION

UL/EN60950 AND DEMKO RECOGNIZED

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE WAVE SOLDERING
PROCESS FOR THROUGH HOLE COMPONENTS

EXTENDED OPERATING TEMP. -40/+85°C

ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO

P1-3:P16-14

1CT:1CT ±3%

P6-8:P11-9

1CT:1CT ±3%

OCL P1-3,P6-8

200µH typ

DCR P1-3,P6-8

0.4Ω max

Cw/w

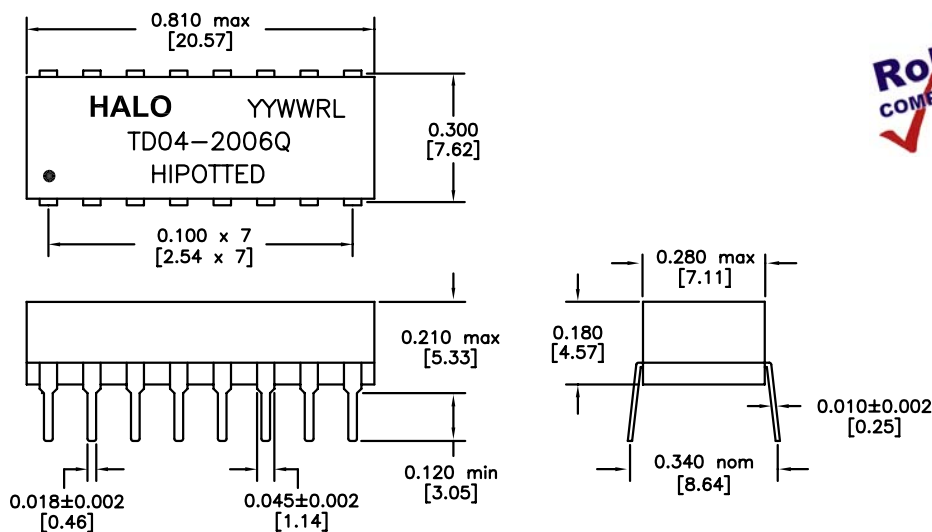
15pF max

LL P1-3,P6-8

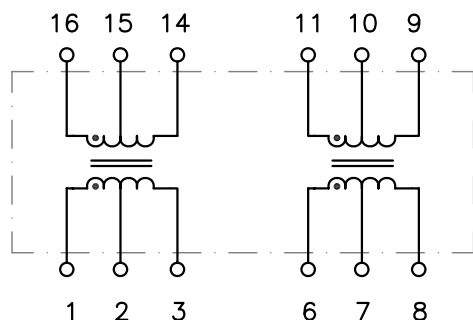
0.3µH max

ISOLATION

2000Vrms



DIMENSIONS: Inch [mm]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	16PIN ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR	10BASE-T	DRAWN	PETER LU	12/12/06	A		
		PART NO.	TD04-2006QRL	CHECKED	LEI KEONG	12/12/06		
	SCALE		NONE	APPROVED	PETER LU	12/12/06		
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